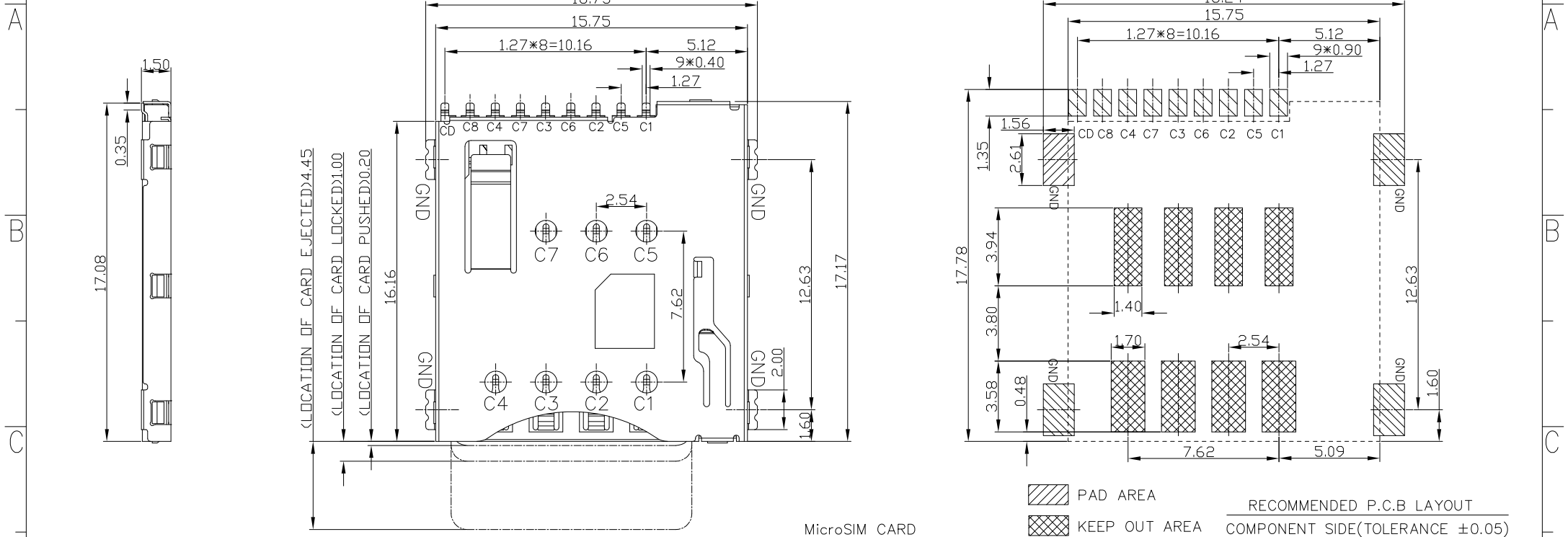


REV.	ECN	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	2016.03.09			



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 15.75LX17.17WX1.50H mm

Weight: Approx 0.4±0.1g

Durability:1500 cycles min.

2.Electrical Characteristics

Contact resistance;

Date Contact:150mΩ max

CD Switch:500mΩ max

Insulation resistance:>1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C,30sec.Max

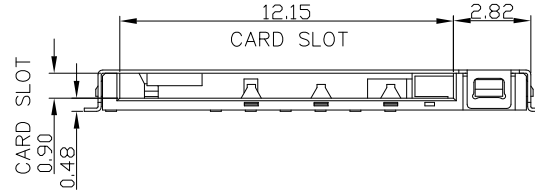
IR reflow: 250°C,5sec.Max

Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity:10%~+95%RH



MicroSIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN



MicroSIM CARD

SCALE 1:2

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	CD SWITCH	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	SMT area:Gold plated
5	COIL SPRING	1	SWP	
6	HEART CAM	1	Hi-temp Thermoplastic	Black UL94V-0
7	CAM PIN	1	Stainless Steel	

MILLIMETERS	INCH	UNITS
X° ± 2'	X° ± 2'	MM
.X ± 0.30	.XX ± 0.012	MAT'L
.XX ± 0.20	.XXX ± 0.008	SEE NOTES
.XXX ± 0.10	.XXXX ± 0.004	FINISH
		SEE NOTES
		QTY
		SEE NOTES

东莞市溪榜电子有限公司		DONG GUAN XI BANG ELECTRONICS CO., LTD.	
PART NUMBER:		TITLE:	
XB-102011422		MicroSIM PUSH H1.5(8P)	
APPD: Sean		DWG NO.:	
CHKD:		A-102011422	
DR: Yang		SCALE	
		1:1	
		SHEET	
		1	
		REV.	
		A	